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states:(71) Applicant: **MITSUI HIGH TEC INC**(72) Inventor: **FUJITA KATSUFUSA**

(74) Representative:

**(54) SEMICONDUCTOR  
DEVICE**

(57) Abstract:

**PROBLEM TO BE SOLVED:** To provide a highly reliable semiconductor device which can deal with enhancement of the heat dissipation properties and electric characteristics and the requirements of small, lightweight multi-terminal semiconductor device.

**SOLUTION:** The semiconductor device 10 comprises a first interposer 14 on which first and second conductor circuit patterns 12, 13 are formed and a second interposer 17 on which third and fourth conductor circuit patterns 15, 16 are formed are bonded formed, respectively, to the surface and backside of a semiconductor element 11 through an example of first and second insulating adhesives 18, 19, i.e., liquid elastomer resins 18a, 19a. The semiconductor device 10 further comprises an example of a plurality of external connection terminals 21, i.e., solder balls 21a, in the form of a

